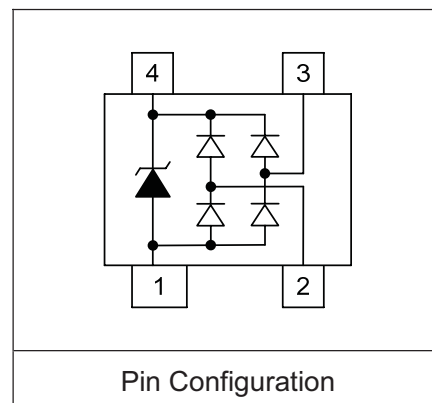
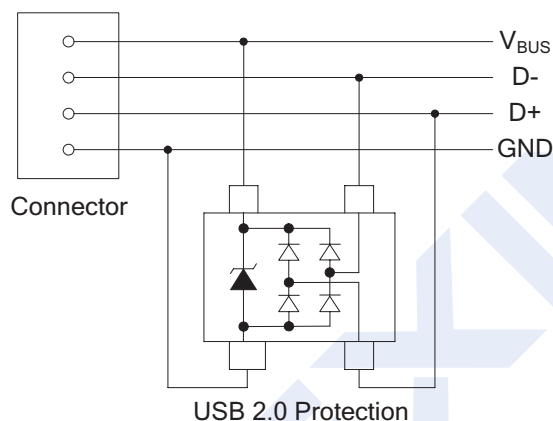


## ESD Protection Devices

## UET14A05L03

## ■ Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOT-143 surface mount package
- Protects two high-speed data lines and one power line
- Array of surge rated, low capacitance diodes
- Working voltage: 5V
- Low leakage current
- Low clamping voltage
- Solid-state silicon avalanche technology



## ■ Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Peak pulse current (tp=8/20μs waveform)	I <sub>PP</sub>	3	A
ESD voltage (Contact discharge)	V <sub>ESD</sub>	±8	kV
ESD voltage (Air discharge)		±15	
Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature range	T <sub>stg</sub>	-55 to +150	

■ Electrical Characteristics T<sub>J</sub> = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse stand-off voltage	V <sub>RWM</sub>				5	V
Reverse breakdown voltage	V <sub>BR</sub>	I <sub>BR</sub> = 1mA	6			
Reverse leakage current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5	μA
Clamping voltage (tp=8/20μs)	V <sub>C</sub>	I <sub>PP</sub> =1A			9.8	V
Clamping voltage (tp=8/20μs)	V <sub>C</sub>	I <sub>PP</sub> =2A			15	
Off state junction capacitance	C <sub>J</sub>	0Vdc, f=1MHz Between I/O pins and GND		0.8		pF

## ■ Marking: B SL3

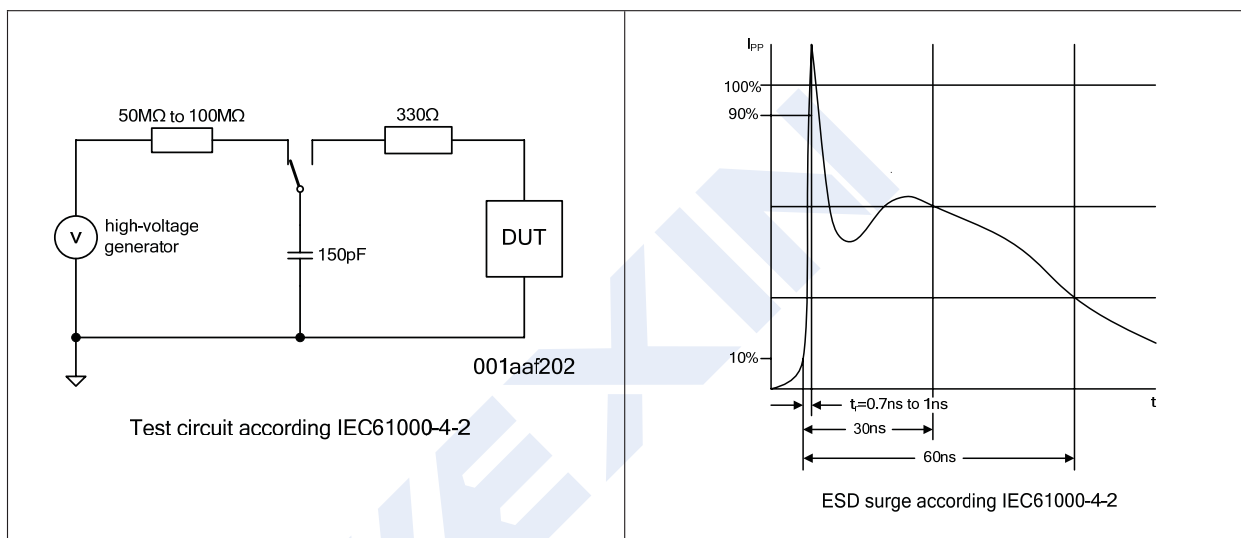
## ESD Protection Devices

## UET14A05L03

## ■ ESD Protection Standards

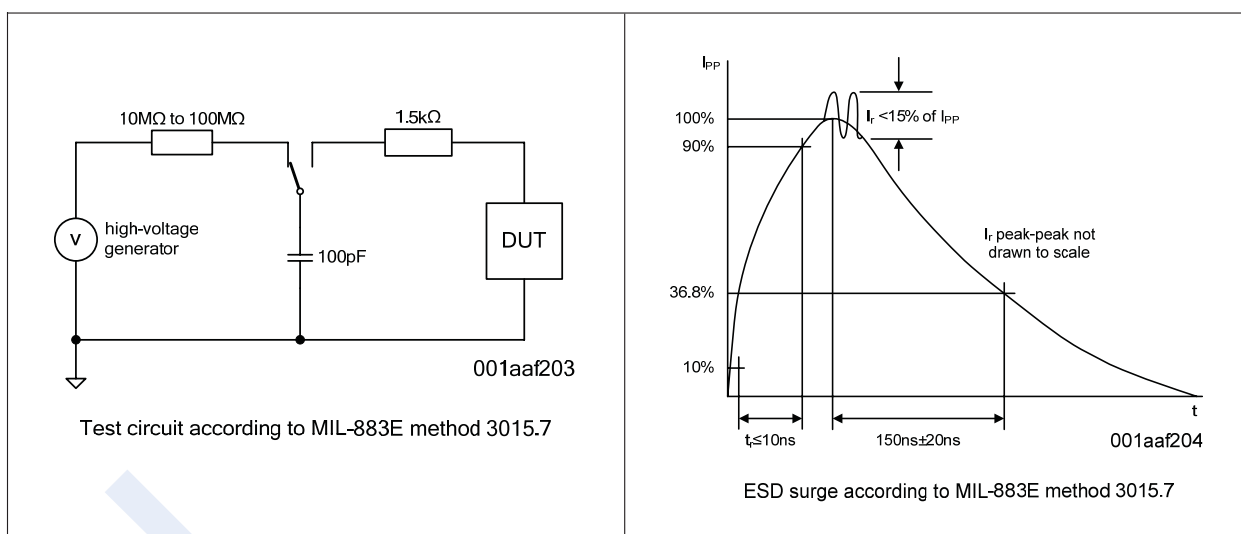
## IEC61000-4-2

Interfaces of consumer electronic equipment are widely specified according to the International Electrotechnical Commission standard IEC61000-4-2. This standard is not targeted towards particular devices but towards general equipment, systems and subsystems that may be involved in electrostatic discharge. consists of a 150pF capacitor and a 330Ω series resistor representing the counterpart to the Device Under Test (DUT).



## Human Body Model (HBM, MIL-883E method 3015.7)

The HBM standard simulates an ESD surge generated by human contact to electronic components.



## ESD Protection Devices

## UET14A05L03

## ■ Package Outline Dimensions

SOT-143

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.79	3.04	0.110	0.120
B	1.90		0.075	
C	0.76	0.93	0.030	0.037
D	0.36	0.50	0.014	0.020
E	1.19	1.40	0.047	0.055
F	-	2.50	-	0.098
G	1.70		0.067	
H	0.15	-	0.006	-
J	0.08	0.15	0.003	0.006
K	-	0.13	-	0.005
L	-	1.14	-	0.045

Recommended Soldering Pad Layout

0.8 (3X)  
0.9 (4X)  
1.9  
1.8  
1.2